POWER-MOS FET
FIELD EFFECT POWER TRANSISTOR

IRFF312,313

1.15 AMPERES
400, 350 VOLTS
$R_{DS(ON)}$ = 5.0 Ω

Preliminary

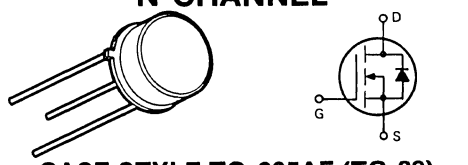
This series of N-Channel Enhancement-mode Power MOSFETs utilizes GE's advanced Power DMOS technology to achieve low on-resistance with excellent device ruggedness and reliability.

This design has been optimized to give superior performance in most switching applications including: switching power supplies, inverters, converters and solenoid/relay drivers. Also, the extended safe operating area with good linear transfer characteristics makes it well suited for many linear applications such as audio amplifiers and servo motors.

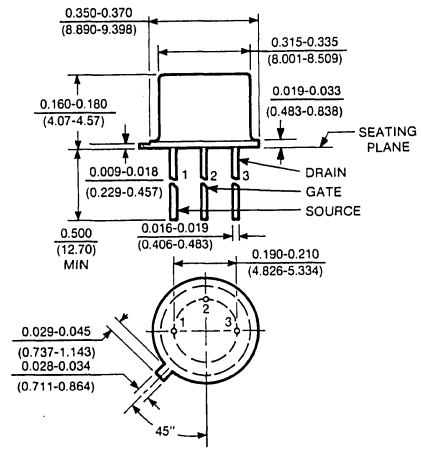
Features

- Polysilicon gate — Improved stability and reliability
- No secondary breakdown — Excellent ruggedness
- Ultra-fast switching — Independent of temperature
- Voltage controlled — High transconductance
- Low input capacitance — Reduced drive requirement
- Excellent thermal stability — Ease of paralleling

N-CHANNEL



CASE STYLE TO-205AF (TO-39)
DIMENSIONS ARE IN INCHES AND (MILLIMETERS)



TYPE	TERM. 1	TERM. 2	TERM. 3
TO-205AF	SOURCE	GATE	DRAIN

maximum ratings (T_C = 25° C) (unless otherwise specified)

RATING	SYMBOL	IRFF312	IRFF313	UNITS
Drain-Source Voltage	V_{DSS}	400	350	Volts
Drain-Gate Voltage, R_{GS} = 1MΩ	V_{DGR}	400	350	Volts
Continuous Drain Current @ T_C = 25°C	I_D	1.15	1.15	A
Pulsed Drain Current(1)	I_{DM}	4.5	4.5	A
Gate-Source Voltage	V_{GS}	±20	±20	Volts
Total Power Dissipation @ T_C = 25°C Derate Above 25°C	P_D	15 0.12	15 0.12	Watts W/°C
Operating and Storage Junction Temperature Range	T_J, T_{STG}	-55 to 150	-55 to 150	°C

thermal characteristics

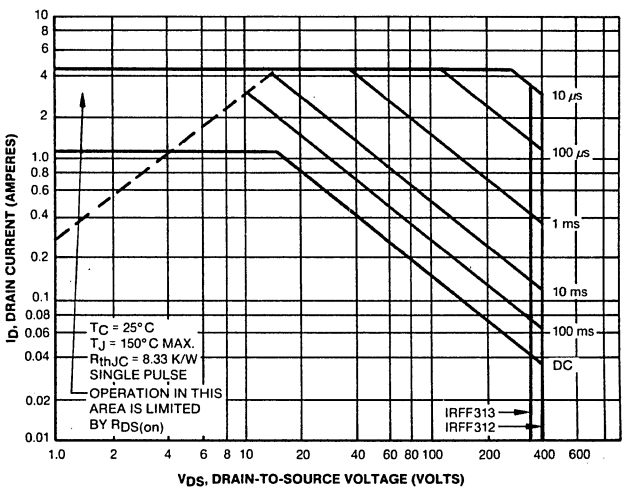
Thermal Resistance, Junction to Case	$R_{\theta JC}$	8.33	8.33	°C/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	175	175	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/16" from Case for 10 Seconds	T_L	260	260	°C

(1) Repetitive Rating: Pulse width limited by max. junction temperature.

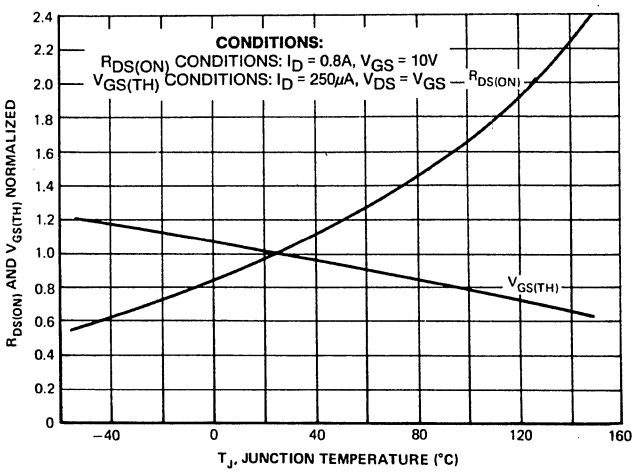
electrical characteristics (T_C = 25°C) (unless otherwise specified)

CHARACTERISTIC		SYMBOL	MIN	TYP	MAX	UNIT
off characteristics						
Drain-Source Breakdown Voltage (V_{GS} = 0V, I_D = 250 μA)	IRFF312 IRFF313	BV_{DSS}	400 350	— —	— —	Volts
Zero Gate Voltage Drain Current (V_{DS} = Max Rating, V_{GS} = 0V, T_C = 25°C) (V_{DS} = Max Rating, × 0.8, V_{GS} = 0V, T_C = 125°C)		I_{DSS}	— —	— —	250 1000	μA
Gate-Source Leakage Current (V_{GS} = ±20V)		I_{GSS}	—	—	±100	nA
on characteristics*						
Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 250 μA)	T_C = 25°C	$V_{GS(TH)}$	2.0	—	4.0	Volts
On-State Drain Current (V_{GS} = 10V, V_{DS} = 10V)		$I_{D(ON)}$	1.15	—	—	Amp
Static Drain-Source On-State Resistance (V_{GS} = 10V, I_D = 0.8A)		$R_{DS(ON)}$	—	—	5.0	Ohms
Forward Transconductance (V_{DS} = 10V, I_D = 0.8A)		g_{fs}	0.4	—	—	mhos
dynamic characteristics						
Input Capacitance	V_{GS} = 0V	C_{iss}	—	385	600	pF
Output Capacitance	V_{DS} = 25V	C_{oss}	—	70	200	pF
Reverse Transfer Capacitance	f = 1 MHz	C_{rss}	—	12	40	pF
switching characteristics*						
Turn-on Delay Time	V_{DS} = 175V	$t_{d(on)}$	—	3	—	ns
Rise Time	I_D = 0.8A, V_{GS} = 15V	t_r	—	10	—	ns
Turn-off Delay Time	R_{GEN} = 50Ω, R_{GS} = 12.5Ω	$t_{d(off)}$	—	5	—	ns
Fall Time	($R_{GS\ (EQUIV.)}$ = 10Ω)	t_f	—	8	—	ns
source-drain diode ratings and characteristics*						
Continuous Source Current		I_S	—	—	1.15	A
Pulsed Source Current		I_{SM}	—	—	4.5	A
Diode Forward Voltage (T_C = 25°C, V_{GS} = 0V, I_S = 1.15A)		V_{SD}	—	—	1.5	Volts
Reverse Recovery Time (I_S = 1.35A, di_S/dt = 100A/μs, Max., T_C = 125°C)		t_{rr}	—	380	—	ns

*Pulse Test: Pulse width ≤ 300 μs, duty cycle ≤ 2%



MAXIMUM SAFE OPERATING AREA



TYPICAL NORMALIZED $R_{DS(ON)}$ AND $V_{GS(TH)}$ VS. TEMP.